


APPLICATION DATA SHEET

Electronic Version v14

Stylesheet Version v14.0

Title of Invention	Heat Sink Riveted to Memory Module with Upper Slots and Open Bottom Edge for Air Flow		
Application Type : regular, utility Attorney Docket Number : ML-16			
Correspondence address: Customer Number: 23933			
			
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as our attorney(s) or agent(s) to prosecute the application identified above, and to transact all business in the United States Patent and Trademark Office connected therewith.

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